

ABSTRACT

This invention provides a prepreg which can yield printed circuit boards with excellent dimensional stability and heat resistance and the ability to be bent and housed at high density in electronic device packages, by impregnating a thin fiber base material with a resin having excellent adhesion with metal foils or fiber base materials, excellent heat resistance and high pliability, as well as a metal foil-clad laminate and printed circuit board employing it. The prepreg of the invention is obtained by impregnating a resin composition containing a resin with an imide structure and a thermosetting resin into a fiber base material with a thickness of 5-50 μm .